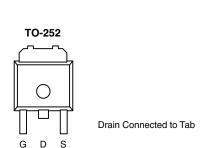




P-Channel 150 V (D-S) MOSFET

PRODUC1	UCT SUMMARY			
V _{DS} (V)	$R_{DS(on)}(\Omega)$ Max.	I _D (A)	Q _g (Typ.)	
	0.306 at $V_{GS} = -10 \text{ V}$	- 8.1		
- 150	0.312 at V _{GS} = - 8 V	- 8	6.2	
	0.335 at V _{GS} = - 6 V	- 7.7		



Ordering Information:

Top View

SUD20P15-306-GE3 (Lead (Pb)-free and Halogen-free)

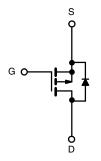
FEATURES

- TrenchFET® Power MOSFET
- 100 % R_q and UIS Tested
- Material categorization: For definitions of compliance please see www.vishay.com/doc?99912



APPLICATIONS

- Power Switch
- DC/DC Converters
- Motor Control
- Load Switch



P-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS	$T_C = 25 ^{\circ}C$, unless ot	herwise noted)			
Parameter	Symbol	Limit	Unit		
Drain-Source Voltage	V _{DS}	- 150	V		
Gate-Source Voltage		V _{GS}			± 20
Continuous Prais Current (T. 150 °C)	T _C = 25 °C		- 8.1		
Continuous Drain Current (T _J = 150 °C)	T _C = 70 °C	I _D	- 6.4		
Pulsed Drain Current (t = 100 μs)	I _{DM}	- 18	A		
Avalanche Current	I _{AS}	- 18			
Single Avalanche Energy ^a	L = 0.1 mH	E _{AS}	16.2	mJ	
Maximum Power Dissipation ^a	T _C = 25 °C	В	41.7 ^b	W	
	T _A = 25 °C ^c	$ P_{D}$	2.1		
Operating Junction and Storage Temperature Range		T _J , T _{stg}	- 55 to 150	°C	

THERMAL RESISTANCE RATINGS				
Parameter	Symbol	Limit	Unit	
Junction-to-Ambient (PCB Mount) ^c	R_{thJA}	60	°C/W	
Junction-to-Case (Drain)	R _{thJC}	3]	

Notes:

- a. Duty cycle \leq 1 %.
- b. See SOA curve for voltage derating.
- c. When mounted on 1" square PCB (FR-4 material).

Document Number: 62861 S13-1671-Rev. A, 29-Jul-13 For technical questions, contact: pmostechsupport@vishav.com

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Static Drain-Source Breakdown Voltage V _{DS} V _{GS} = 0 V, I _D = -250 μA -150 V _{DS} = V _{GS} V _{DS} = V _{DS} V _{DS} = 250 μA -2 -4 V _{DS} = V _{DS} V _{DS} = V _{DS} V _{DS} = 250 μA -2 -4 V _{DS} = V _{DS} V _{DS} = 250 μA -2 -4 V _{DS} = V _{DS} V _{DS} = 150 V, V _{GS} = 0 V ± 250 nA V _{DS} = 150 V, V _{GS} = 0 V ± 250 nA V _{DS} = -150 V, V _{GS} = 0 V V _{DS} = -150 V, V _{GS} = 0 V V _{DS} = -150 V, V _{GS} = 0 V V _{DS} = -150 V, V _{GS} = 0 V V _{DS} = -150 V, V _{GS} = 0 V, V _{DS} = -150 V, V _{GS} = 0 V, V _{DS} = -150 V, V _{GS} = 0 V, V _{DS} = -150 V, V _{GS} = 0 V, V _{DS} = -150 V, V _{GS} = 0 V, V _{DS} = -150 V, V _{DS} = -10 V -10 V _{DS} = -150 V, V _{DS} = -10 V -10 V _{DS} = -150 V, V _{DS} = -10 V -10 V _{DS} = -10 V, V _{DS} = -10 V -10 V _{DS} = -10 V, V _{DS} = -10 V -10 V _{DS} = -10 V, V _{DS} = -10 V -10 V _{DS} = -10 V, V _{DS} = -10 V -10 V _{DS} = -10 V, V _{DS} = -10 V -10 V _{DS} = -10 V, V _{DS} = -10 V -10 V _{DS} = -10 V,	SPECIFICATIONS (T _J = 25	°C, unless o	otherwise noted)				
$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$	Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit
$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$	Static						
$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$	Drain-Source Breakdown Voltage	V_{DS}	$V_{GS} = 0 \text{ V}, I_{D} = -250 \ \mu\text{A}$	- 150			V
	Gate Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = -250 \mu A$	- 2		- 4	
$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$	Gate-Body Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 250	nA
$\begin{array}{c ccccccccccccccccccccccccccccccccccc$			V _{DS} = - 150 V, V _{GS} = 0 V			- 1	μΑ
$\begin{array}{c ccccccccccccccccccccccccccccccccccc$	Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = - 150 V, V _{GS} = 0 V, T _J = 125 °C			- 50	
$\begin{array}{c} V_{GS} = -10 \text{ V, } I_{D} = -3 \text{ A} & 0.225 & 0.306 \\ V_{GS} = -8 \text{ V, } I_{D} = -3 \text{ A} & 0.260 & 0.312 \\ V_{GS} = -6 \text{ V, } I_{D} = -3 \text{ A} & 0.260 & 0.312 \\ V_{GS} = -6 \text{ V, } I_{D} = -3 \text{ A} & 0.260 & 0.312 \\ V_{GS} = -6 \text{ V, } I_{D} = -3 \text{ A} & 0.278 & 0.335 \\ \hline \\ \text{Forward Transconductance}^a & g_{fs} & V_{DS} = -20 \text{ V, } I_{D} = -3 \text{ A} & 40 & 8 \\ \hline \\ \textbf{Dynamic}^b \\ \textbf{Input Capacitance} & C_{iss} \\ \textbf{Output Capacitance} & C_{oss} \\ \textbf{Reverse Transfer Capacitance} & C_{rss} \\ \textbf{Total Gate Charge}^c & Q_g \\ \textbf{Gate-Source Charge}^c & Q_{gs} \\ \textbf{Gate-Drain Charge}^c & Q_{gd} \\ \textbf{Gate Resistance} & R_g & f = 1 \text{ MHz} & 0.6 & 3.1 & 6.2 & \Omega \\ \textbf{Turn-On Delay Time}^c & t_f \\ \textbf{Turn-Off Delay Time}^c & t_f \\ \textbf{Turn-Off Delay Time}^c & t_f \\ \textbf{Turn-On Delay Time}^c & t_f \\ \textbf{Turn-On Delay Time}^c & t_f \\ \textbf{Turn-On Delay Time}^c & t_f \\ \textbf{Turn-Off Delay Time}^c $			V _{DS} = - 150 V, V _{GS} = 0 V, T _J = 150 °C			- 250	
$\begin{array}{c ccccccccccccccccccccccccccccccccccc$	On-State Drain Current ^a	I _{D(on)}	$V_{DS} \le -10 \text{ V}, V_{GS} = -10 \text{ V}$	- 10			Α
$\begin{array}{c ccccccccccccccccccccccccccccccccccc$			V _{GS} = - 10 V, I _D = - 3 A		0.225	0.306	Ω
$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$	Drain-Source On-State Resistance ^a	R _{DS(on)}	V _{GS} = -8 V, I _D = -3 A		0.260	0.312	
$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$			V _{GS} = - 6 V, I _D = - 3 A		0.278	0.335	
$ \begin{array}{ c c c c c c } \hline \text{Input Capacitance} & & & & & & & & & & & & & & & & & & &$	Forward Transconductance ^a	9 _{fs}	V _{DS} = - 20 V, I _D = - 3 A		40		S
$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$	Dynamic ^b						
$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$	Input Capacitance	C _{iss}			1265		pF
$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$	Output Capacitance		V _{GS} = 0 V, V _{DS} = -75 V, f = 1 MHz		56		
$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$	Reverse Transfer Capacitance				39		
$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$	Total Gate Charge ^c	Q_g			27	41	nC
$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$	Gate-Source Charge ^c	Q_{gs}	$V_{DS} = -75 \text{ V}, V_{GS} = -10 \text{ V}, I_{D} = -3 \text{ A}$		6.2		
$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$	Gate-Drain Charge ^c				7.1		
$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$	Gate Resistance	R_{g}	f = 1 MHz	0.6	3.1	6.2	Ω
$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$	Turn-On Delay Time ^c	t _{d(on)}			10	20	
$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$	Rise Time ^c				11	20	
	Turn-Off Delay Time ^c	t _{d(off)}			27	41	
$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$	Fall Time ^c	t _f			12	20	
Turn-Off Delay Time ^c $t_{d(off)}$ $I_D \cong -2.5 \text{ A}, V_{GEN} = -8 \text{ V}, R_g = 1 \Omega$ 24 36 Fall Time ^c t_f 10 20	Turn-On Delay Time ^c	t _{d(on)}			11	20	ns
Fall Time ^c t _f 10 20	Rise Time ^c	t _r	V_{DD} = - 75 V, R_L = 30 Ω		9	18	
	Turn-Off Delay Time ^c	t _{d(off)}	$I_D \cong$ - 2.5 A, V_{GEN} = - 8 V, R_g = 1 Ω		24	36	
Drain-Source Body Diode Ratings and Characteristics T _C = 25 °C ^b	Fall Time ^c	t _f			10	20	
, J	Drain-Source Body Diode Ratings ar	nd Characteri	stics T _C = 25 °C ^b				
	Continuous Current	Is				- 8.1	
Pulsed Current (t = 100 µs) I _{SM} - 18	Pulsed Current (t = 100 μs)	I _{SM}				- 18	A
Forward Voltage ^a V_{SD} $I_F = -2.5 \text{ A}, V_{GS} = 0 \text{ V}$ $-0.8 -1.5 \text{ V}$	Forward Voltage ^a	V_{SD}	I _F = - 2.5 A, V _{GS} = 0 V		- 0.8	- 1.5	V
	Reverse Recovery Time		I _F = - 2.5 A, dl/dt = 100 A/μs		58	87	ns
Peak Reverse Recovery Current $I_{RM(REC)}$ $I_F = -2.5 \text{ A}$, $dI/dt = 100 \text{ A/µs}$ 5.5 8.3 A	Peak Reverse Recovery Current	I _{RM(REC)}			5.5	8.3	Α
	Reverse Recovery Charge				150	225	nC

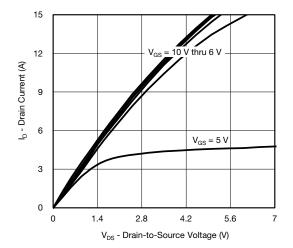
Notes

- a. Pulse test; pulse width \leq 300 $\mu s,$ duty cycle \leq 2 %.
- b. Guaranteed by design, not subject to production testing.
- c. Independent of operating temperature.

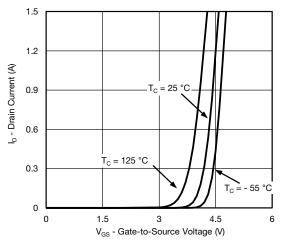
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



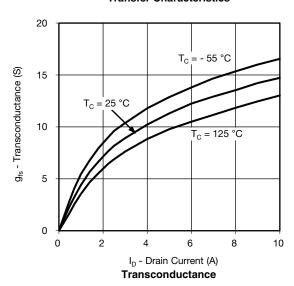
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

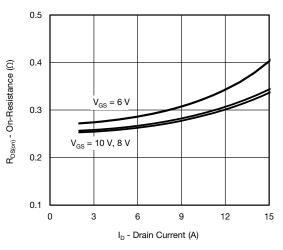


Output Characteristics

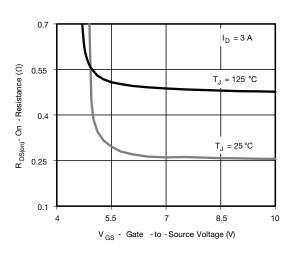


Transfer Characteristics

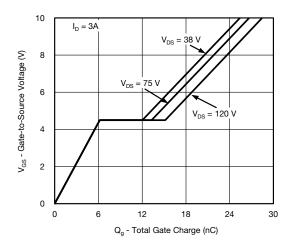




On-Resistance vs. Drain Current



On-Resistance vs. Gate-to-Source Voltage

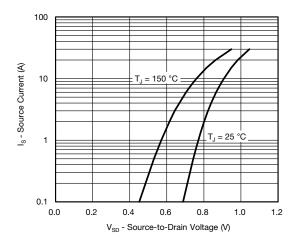


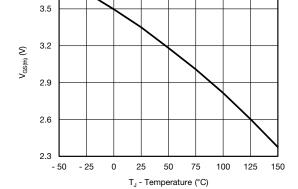
Gate Charge

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l_D = 250 μΑ

TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

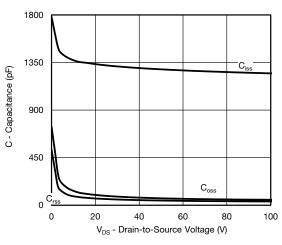


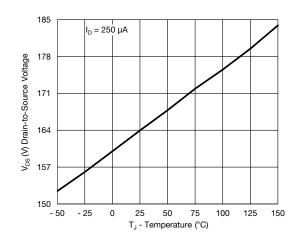


3.8

Source-Drain Diode Forward Voltage

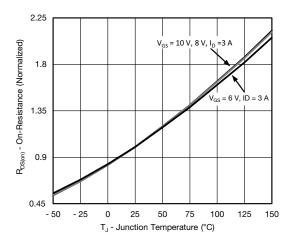
Threshold Voltage

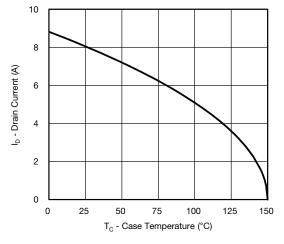




Capacitance

Drain Source Breakdown vs. Junction Temperature



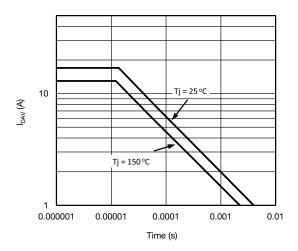


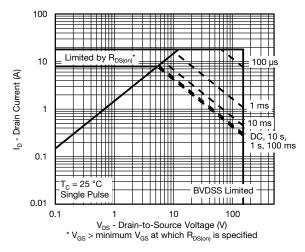
On-Resistance vs. Junction Temperature

Current Derating



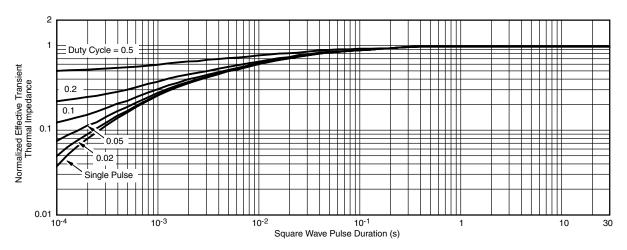
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)





Single Pulse Avalanche Current Capability vs. Time





Normalized Thermal Transient Impedance, Junction-to-Case

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